

45 4580 03 MP T2,0

High-current contact elements



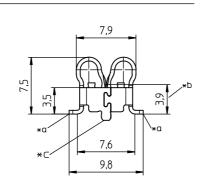
High-current contact bush with positioning pegs, mateable from top or bottom direction, for tab contacts 1.5–2.0 mm, for printed circuit boards or lead frames



4580 03 MP T2,0

33.8

45



Environmental conditions

Temperature range -40 °C/+120 °C

Materials

Contact CuCr alloy, tin-plated

Mechanical data

Mating with tab contact 5.3 mm x 1.5–2.0 mm applicable for reflow soldering on

printed circuit board

applicable for laser welding on

lead frame, e.g. Cu, tin-plated

Mating cycles ≤ 5

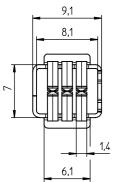
Insertion force tab contact 1.5 mm

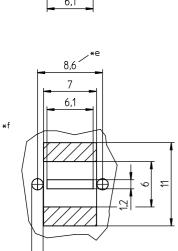
35 N \pm 10 N - top or bottom entry tab contact 2.0 mm

35 N ± 10 N – top entry 50 N ± 10 N – bottom entry

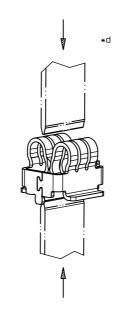
Withdrawal force $6 \text{ N} + 10/-3 \text{ N}^1$

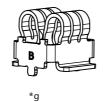
¹ measured with polished steel test tabs





Ø 1,5





Electrical data (at Tamb 20 °C)

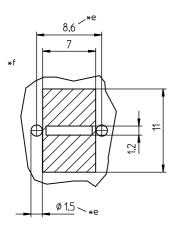
Contact resistance $< 0.5 \text{ m}\Omega$ Rated current $\leq 60 \text{ A}^{1}$

 $^{\rm 1}$ depending on the connection to the printed circuit board/lead frame, installation situation and heat dissipation



45 45

4580 03 MP T2,0



- *a supporting surface for soldering dimensions per solder pad min. 7.0 mm x 2.5 mm
- *b height contact point
- *c positioning peg
- *d mateable from top or bottom direction
- *e bore holes for positioning pegs
- *f circuit board layout (example)
- *g marking B for type 4580 03 MP T2,0



45 4580 03 MP T2,0

Designation	Pole Number	PU (Pieces)	MDQ (Pieces)
4580 03 MP T2,0 V12VP12	1	350	2100

Packaging:

on reel